

Title (en)

DEVICE FOR THERMAL TREATMENT OF SUBSTRATES

Title (de)

VORRICHTUNG ZUM THERMISCHEN BEHANDELN VON SUBSTRATEN

Title (fr)

DISPOSITIF DE TRAITEMENT THERMIQUE DE SUBSTRATS

Publication

EP 1250710 A1 20021023 (DE)

Application

EP 01901179 A 20010119

Priority

- DE 10003639 A 20000128
- EP 0100607 W 20010119

Abstract (en)

[origin: WO0156064A1] The aim of the invention is to reduce the formation of scratches in a device for the thermal treatment of substrates, in particular, semiconductor substrates, in a chamber in which the substrate is placed upon support elements. According to the invention, said aim is achieved by means of displaceable support elements.

IPC 1-7

H01L 21/00

IPC 8 full level

H01L 21/683 (2006.01); **H01L 21/00** (2006.01); **H01L 21/324** (2006.01); **H01L 21/687** (2006.01)

CPC (source: EP KR US)

H01L 21/324 (2013.01 - KR); **H01L 21/67115** (2013.01 - EP US); **H01L 21/68742** (2013.01 - EP US); **H01L 21/6875** (2013.01 - EP US); **H01L 21/68785** (2013.01 - EP US)

Citation (search report)

See references of WO 0156064A1

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

WO 0156064 A1 20010802; DE 10003639 A1 20010809; DE 10003639 C2 20030618; EP 1250710 A1 20021023; JP 2003525524 A 20030826; JP 4828761 B2 20111130; KR 100744215 B1 20070730; KR 20020071971 A 20020913; TW 488009 B 20020521; US 2004029065 A1 20040212; US 6953338 B2 20051011

DOCDB simple family (application)

EP 0100607 W 20010119; DE 10003639 A 20000128; EP 01901179 A 20010119; JP 2001555121 A 20010119; KR 20027009638 A 20020726; TW 90101432 A 20010129; US 18259403 A 20030728